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ABSTRACT OF THE DISCLOSURE

PRINTED CIRCUIT BOARD AND ITS MANUFACTURING METHOD

A conductor pattern is formed on a resin film which is made of a thermoplastic resin. Each single-sided conductor pattern film has via-holes filled with an electrically conductive paste. A printed conductor pattern and a printed resistor are formed on a ceramic substrate. The single-sided conductor pattern films are laminated on the ceramic substrate. Then, the multilayered assembly is heated and pressed from both sides thereof to obtain a printed circuit board. During the heat and press treatment, respective single-sided conductor pattern films and the ceramic substrate bond together while the interlayer connection is obtained between the conductor patterns as well as between the conductor pattern and the printed conductor pattern.

(Figs. 1F - 1H)



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